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Details	
Product Status	Obsolete
Number of LABs/CLBs	234720
Number of Logic Elements/Cells	622000
Total RAM Bits	51200000
Number of I/O	552
Number of Gates	-
Voltage - Supply	0.82V ~ 0.88V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	1152-BBGA, FCBGA
Supplier Device Package	1152-FBGA (35x35)
Purchase URL	https://www.e-xfl.com/product-detail/intel/5sgxma7h3f35i3n

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Table 3. Absolute Maximum Ratings for Stratix V Devices (Part 2 of 2)

Symbol	Description	Minimum	Maximum	Unit
V _{CCD_FPLL}	PLL digital power supply	-0.5	1.8	V
V _{CCA_FPLL}	PLL analog power supply	-0.5	3.4	V
V _I	DC input voltage	-0.5	3.8	V
T _J	Operating junction temperature	-55	125	°C
T _{STG}	Storage temperature (No bias)	-65	150	°C
I _{OUT}	DC output current per pin	-25	40	mA

Table 4 lists the absolute conditions for the transceiver power supply for Stratix V GX, GS, and GT devices.

Table 4. Transceiver Power Supply Absolute Conditions for Stratix V GX, GS, and GT Devices

Symbol	Description	Devices	Minimum	Maximum	Unit
V _{CCA_GXBL}	Transceiver channel PLL power supply (left side)	GX, GS, GT	-0.5	3.75	V
V _{CCA_GXBR}	Transceiver channel PLL power supply (right side)	GX, GS	-0.5	3.75	V
V _{CCA_GTBR}	Transceiver channel PLL power supply (right side)	GT	-0.5	3.75	V
V _{CCHIP_L}	Transceiver hard IP power supply (left side)	GX, GS, GT	-0.5	1.35	V
V _{CCHIP_R}	Transceiver hard IP power supply (right side)	GX, GS, GT	-0.5	1.35	V
V _{CCHSSI_L}	Transceiver PCS power supply (left side)	GX, GS, GT	-0.5	1.35	V
V _{CCHSSI_R}	Transceiver PCS power supply (right side)	GX, GS, GT	-0.5	1.35	V
V _{CCR_GXBL}	Receiver analog power supply (left side)	GX, GS, GT	-0.5	1.35	V
V _{CCR_GXBR}	Receiver analog power supply (right side)	GX, GS, GT	-0.5	1.35	V
V _{CCR_GTBR}	Receiver analog power supply for GT channels (right side)	GT	-0.5	1.35	V
V _{CCT_GXBL}	Transmitter analog power supply (left side)	GX, GS, GT	-0.5	1.35	V
V _{CCT_GXBR}	Transmitter analog power supply (right side)	GX, GS, GT	-0.5	1.35	V
V _{CCT_GTBR}	Transmitter analog power supply for GT channels (right side)	GT	-0.5	1.35	V
V _{CCL_GTBR}	Transmitter clock network power supply (right side)	GT	-0.5	1.35	V
V _{CCH_GXBL}	Transmitter output buffer power supply (left side)	GX, GS, GT	-0.5	1.8	V
V _{CCH_GXBR}	Transmitter output buffer power supply (right side)	GX, GS, GT	-0.5	1.8	V

Maximum Allowed Overshoot and Undershoot Voltage

During transitions, input signals may overshoot to the voltage shown in Table 5 and undershoot to -2.0 V for input currents less than 100 mA and periods shorter than 20 ns.

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Recommended Operating Conditions

This section lists the functional operating limits for the AC and DC parameters for Stratix V devices. Table 6 lists the steady-state voltage and current values expected from Stratix V devices. Power supply ramps must all be strictly monotonic, without plateaus.

Table 6. Recommended Operating Conditions for Stratix V Devices (Part 1 of 2)

Symbol	Description	Condition	Min ⁽⁴⁾	Тур	Max ⁽⁴⁾	Unit
	Core voltage and periphery circuitry power supply (C1, C2, I2, and I3YY speed grades)	_	0.87	0.9	0.93	V
V _{CC}	Core voltage and periphery circuitry power supply (C2L, C3, C4, I2L, I3, I3L, and I4 speed grades) (3)	_	0.82	0.85	0.88	V
V _{CCPT}	Power supply for programmable power technology	_	1.45	1.50	1.55	V
V _{CC_AUX}	Auxiliary supply for the programmable power technology	_	2.375	2.5	2.625	V
V (1)	I/O pre-driver (3.0 V) power supply		2.85	3.0	3.15	V
V _{CCPD} ⁽¹⁾	I/O pre-driver (2.5 V) power supply		2.375	2.5	2.625	V
	I/O buffers (3.0 V) power supply	_	2.85	3.0	3.15	٧
	I/O buffers (2.5 V) power supply	_	2.375	2.5	2.625	V
	I/O buffers (1.8 V) power supply	_	1.71	1.8	1.89	٧
V_{CCIO}	I/O buffers (1.5 V) power supply	_	1.425	1.5	1.575	V
	I/O buffers (1.35 V) power supply		1.283	1.35	1.45	V
	I/O buffers (1.25 V) power supply		1.19	1.25	1.31	V
	I/O buffers (1.2 V) power supply	_	1.14	1.2	1.26	V
	Configuration pins (3.0 V) power supply		2.85	3.0	3.15	V
V_{CCPGM}	Configuration pins (2.5 V) power supply	_	2.375	2.5	2.625	V
	Configuration pins (1.8 V) power supply	_	1.71	1.8	1.89	V
V _{CCA_FPLL}	PLL analog voltage regulator power supply		2.375	2.5	2.625	V
V _{CCD_FPLL}	PLL digital voltage regulator power supply		1.45	1.5	1.55	V
V _{CCBAT} (2)	Battery back-up power supply (For design security volatile key register)	_	1.2	_	3.0	V
V _I	DC input voltage	_	-0.5	_	3.6	V
V ₀	Output voltage	_	0	_	V _{CCIO}	V
т.	Operating junction temperature	Commercial	0	_	85	°C
T _J	Operating junction temperature	Industrial	-40	_	100	°C

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Table 11. OCT Calibration Accuracy Specifications for Stratix V Devices (1) (Part 2 of 2)

				Calibratio	n Accuracy		
Symbol	Description	Conditions	C1	C2,I2	C3,I3, I3YY	C4,I4	Unit
50-Ω R _S	Internal series termination with calibration (50- Ω setting)	V _{CCIO} = 3.0, 2.5, 1.8, 1.5, 1.2 V	±15	±15	±15	±15	%
$34\text{-}\Omega$ and $40\text{-}\Omega$ R_S	Internal series termination with calibration (34- Ω and 40- Ω setting)	V _{CCIO} = 1.5, 1.35, 1.25, 1.2 V	±15	±15	±15	±15	%
48 - Ω , 60 - Ω , 80 - Ω , and 240 - Ω R _S	Internal series termination with calibration (48- Ω , 60- Ω , 80- Ω , and 240- Ω setting)	V _{CCIO} = 1.2 V	±15	±15	±15	±15	%
50-Ω R _T	Internal parallel termination with calibration (50-Ω setting)	V _{CCIO} = 2.5, 1.8, 1.5, 1.2 V	-10 to +40	-10 to +40	-10 to +40	-10 to +40	%
$\begin{array}{c} 20\text{-}\Omega,30\text{-}\Omega,\\ 40\text{-}\Omega,60\text{-}\Omega,\\ \text{and}\\ 120\text{-}\OmegaR_T \end{array}$	Internal parallel termination with calibration (20- Ω , 30- Ω , 40- Ω , 60- Ω , and 120- Ω setting)	V _{CCIO} = 1.5, 1.35, 1.25 V	-10 to +40	-10 to +40	-10 to +40	-10 to +40	%
60- Ω and 120- Ω R _T	Internal parallel termination with calibration (60- Ω and 120- Ω setting)	V _{CCIO} = 1.2	-10 to +40	-10 to +40	-10 to +40	-10 to +40	%
$\begin{array}{c} \textbf{25-}\Omega \\ \textbf{R}_{S_left_shift} \end{array}$	Internal left shift series termination with calibration (25- Ω R _{S_left_shift} setting)	V _{CCIO} = 3.0, 2.5, 1.8, 1.5, 1.2 V	±15	±15	±15	±15	%

Note to Table 11:

Table 12 lists the Stratix V OCT without calibration resistance tolerance to PVT changes.

Table 12. OCT Without Calibration Resistance Tolerance Specifications for Stratix V Devices (Part 1 of 2)

			Resistance Tolerance				
Symbol	Description	Conditions	C1	C2,I2	C3, I3, I3YY	C4, I4	Unit
25-Ω R, 50-Ω R _S	Internal series termination without calibration (25- Ω setting)	V _{CCIO} = 3.0 and 2.5 V	±30	±30	±40	±40	%
25-Ω R _S	Internal series termination without calibration (25- Ω setting)	V _{CCIO} = 1.8 and 1.5 V	±30	±30	±40	±40	%
25-Ω R _S	Internal series termination without calibration (25- Ω setting)	V _{CCIO} = 1.2 V	±35	±35	±50	±50	%

⁽¹⁾ OCT calibration accuracy is valid at the time of calibration only.

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Table 13. OCT Variation after Power-Up Calibration for Stratix V Devices (Part 2 of 2) (1)

Symbol	Description	V _{CCIO} (V)	Typical	Unit
		3.0	0.189	
		2.5	0.208	
dR/dT	OCT variation with temperature without recalibration	1.8	0.266	%/°C
	Willout recalibration	1.5	0.273	1
		1.2	0.317	

Note to Table 13:

(1) Valid for a V_{CCIO} range of $\pm 5\%$ and a temperature range of 0° to $85^\circ\text{C}.$

Pin Capacitance

Table 14 lists the Stratix V device family pin capacitance.

Table 14. Pin Capacitance for Stratix V Devices

Symbol	Description	Value	Unit
C _{IOTB}	Input capacitance on the top and bottom I/O pins	6	pF
C _{IOLR}	Input capacitance on the left and right I/O pins	6	pF
C _{OUTFB}	Input capacitance on dual-purpose clock output and feedback pins	6	pF

Hot Socketing

Table 15 lists the hot socketing specifications for Stratix V devices.

Table 15. Hot Socketing Specifications for Stratix V Devices

Symbol	Description	Maximum
I _{IOPIN (DC)}	DC current per I/O pin	300 μΑ
I _{IOPIN (AC)}	AC current per I/O pin	8 mA ⁽¹⁾
I _{XCVR-TX (DC)}	DC current per transceiver transmitter pin	100 mA
I _{XCVR-RX (DC)}	DC current per transceiver receiver pin	50 mA

Note to Table 15:

(1) The I/O ramp rate is 10 ns or more. For ramp rates faster than 10 ns, $|I_{IOPIN}| = C dv/dt$, in which C is the I/O pin capacitance and dv/dt is the slew rate.

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Internal Weak Pull-Up Resistor

Table 16 lists the weak pull-up resistor values for Stratix V devices.

Table 16. Internal Weak Pull-Up Resistor for Stratix V Devices (1), (2)

Symbol	Description	V _{CC10} Conditions (V) ⁽³⁾	Value ⁽⁴⁾	Unit
		3.0 ±5%	25	kΩ
		2.5 ±5%	25	kΩ
	Value of the I/O pin pull-up resistor before	1.8 ±5%	25	kΩ
R _{PU}	and during configuration, as well as user mode if you enable the programmable	1.5 ±5%	25	kΩ
	pull-up resistor option.	1.35 ±5%	25	kΩ
		1.25 ±5% 25		kΩ
		1.2 ±5%	25	kΩ

Notes to Table 16:

- (1) All I/O pins have an option to enable the weak pull-up resistor except the configuration, test, and JTAG pins.
- (2) The internal weak pull-down feature is only available for the JTAG TCK pin. The typical value for this internal weak pull-down resistor is approximately 25 k Ω .
- (3) The pin pull-up resistance values may be lower if an external source drives the pin higher than V_{CCIO} .
- (4) These specifications are valid with a ±10% tolerance to cover changes over PVT.

I/O Standard Specifications

Table 17 through Table 22 list the input voltage (V_{IH} and V_{IL}), output voltage (V_{OH} and V_{OL}), and current drive characteristics (I_{OH} and I_{OL}) for various I/O standards supported by Stratix V devices. These tables also show the Stratix V device family I/O standard specifications. The V_{OL} and V_{OH} values are valid at the corresponding I_{OH} and I_{OL} , respectively.

For an explanation of the terms used in Table 17 through Table 22, refer to "Glossary" on page 65. For tolerance calculations across all SSTL and HSTL I/O standards, refer to Altera knowledge base solution rd07262012_486.

Table 17. Single-Ended I/O Standards for Stratix V Devices

1/0		V _{CCIO} (V)		VII	_(V)	V _{IH}	(V)	V _{OL} (V)	V _{OH} (V)	I _{OL}	I _{OH}
Standard	Min	Тур	Max	Min	Max	Min	Max	Max	Min	(mĀ)	(mA)
LVTTL	2.85	3	3.15	-0.3	0.8	1.7	3.6	0.4	2.4	2	-2
LVCMOS	2.85	3	3.15	-0.3	0.8	1.7	3.6	0.2	V _{CCIO} - 0.2	0.1	-0.1
2.5 V	2.375	2.5	2.625	-0.3	0.7	1.7	3.6	0.4	2	1	-1
1.8 V	1.71	1.8	1.89	-0.3	0.35 * V _{CCIO}	0.65 * V _{CCIO}	V _{CCIO} + 0.3	0.45	V _{CCIO} – 0.45	2	-2
1.5 V	1.425	1.5	1.575	-0.3	0.35 * V _{CCIO}	0.65 * V _{CCIO}	V _{CCIO} + 0.3	0.25 * V _{CCIO}	0.75 * V _{CCIO}	2	-2
1.2 V	1.14	1.2	1.26	-0.3	0.35 * V _{CCIO}	0.65 * V _{CCIO}	V _{CCIO} + 0.3	0.25 * V _{CCIO}	0.75 * V _{CCIO}	2	-2

Table 23. Transceiver Specifications for Stratix V GX and GS Devices (1) (Part 2 of 7)

Symbol/	Conditions	Trai	nsceive Grade	r Speed 1	Trai	nsceive Grade	r Speed 2	Transceiver Speed Grade 3			Unit
Description		Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	
Spread-spectrum downspread	PCle	_	0 to -0.5	_	_	0 to -0.5	_	_	0 to -0.5	_	%
On-chip termination resistors (21)	_	_	100	_	_	100	_	_	100	_	Ω
Absolute V _{MAX} ⁽⁵⁾	Dedicated reference clock pin	_	_	1.6	_	_	1.6	_	_	1.6	V
	RX reference clock pin		_	1.2	_	_	1.2	_	_	1.2	
Absolute V _{MIN}	_	-0.4		_	-0.4		_	-0.4	_	_	V
Peak-to-peak differential input voltage	_	200	_	1600	200	_	1600	200	_	1600	mV
V _{ICM} (AC	Dedicated reference clock pin	1050/1000/900/850 (2)			1050/1000/900/850 ⁽²⁾ 1050/1000/900/850 ⁽²⁾			00/850 ⁽²⁾	mV		
coupled) ⁽³⁾	RX reference clock pin	1.	.0/0.9/0	.85 ⁽⁴⁾	1.	0/0.9/0	.85 ⁽⁴⁾	1.0/0.9/0.85 (4)		V	
V _{ICM} (DC coupled)	HCSL I/O standard for PCIe reference clock	250	_	550	250	_	550	250	_	550	mV
	100 Hz	_	_	-70	_	_	-70	_	_	-70	dBc/Hz
Transmitter	1 kHz	_	_	-90	_	_	-90	_	_	-90	dBc/Hz
REFCLK Phase Noise	10 kHz		_	-100	_	_	-100	_	_	-100	dBc/Hz
(622 MHz) ⁽²⁰⁾	100 kHz	_	_	-110	_	_	-110	_	_	-110	dBc/Hz
	≥1 MHz	_	_	-120		_	-120		_	-120	dBc/Hz
Transmitter REFCLK Phase Jitter (100 MHz) (17)	10 kHz to 1.5 MHz (PCle)	_	_	3	_	_	3	_	_	3	ps (rms)
R _{REF} (19)	_	_	1800 ±1%	_	_	1800 ±1%	_	_	180 0 ±1%	_	Ω
Transceiver Clock	<u> </u>			_			_				
fixedclk clock frequency	PCIe Receiver Detect	_	100 or 125	_	_	100 or 125	_	_	100 or 125	_	MHz

Table 23. Transceiver Specifications for Stratix V GX and GS Devices (1) (Part 4 of 7)

Symbol/	Conditions	Tra	nsceive Grade	r Speed 1	Trai	nsceive Grade		Trai	nsceive Grade	r Speed 3	Unit
Description		Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	
	85– Ω setting	_	85 ± 30%	_	_	85 ± 30%	_	_	85 ± 30%	_	Ω
Differential on-	100–Ω setting	_	100 ± 30%	_	_	100 ± 30%	_	_	100 ± 30%	_	Ω
chip termination resistors (21)	120–Ω setting	_	120 ± 30%		_	120 ± 30%		_	120 ± 30%	_	Ω
	150-Ω setting	_	150 ± 30%	_	_	150 ± 30%	_	_	150 ± 30%	_	Ω
	V _{CCR_GXB} = 0.85 V or 0.9 V full bandwidth	_	600	_	_	600	_	_	600	_	mV
V _{ICM} (AC and DC coupled)	V _{CCR_GXB} = 0.85 V or 0.9 V half bandwidth	_	600	_	_	600	_	_	600	_	mV
coupleu)	V _{CCR_GXB} = 1.0 V/1.05 V full bandwidth	_	700	_	_	700	_	_	700	_	mV
	V _{CCR_GXB} = 1.0 V half bandwidth	_	750	_	_	750	_	_	750	_	mV
t _{LTR} (11)	_	_	_	10	_	_	10	_	_	10	μs
t _{LTD} (12)	_	4	_		4			4		_	μs
t _{LTD_manual} (13)	_	4	_		4	_		4	_		μs
t _{LTR_LTD_manual} (14)	_	15	_	_	15		_	15		_	μs
Run Length	_		_	200		_	200	_		200	UI
Programmable equalization (AC Gain) ⁽¹⁰⁾	Full bandwidth (6.25 GHz) Half bandwidth (3.125 GHz)	_	_	16	_	_	16	_	_	16	dB

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Table 23. Transceiver Specifications for Stratix V GX and GS Devices (1) (Part 7 of 7)

Symbol/ Description	Conditions	Transceiver Speed Grade 1			Transceiver Speed Grade 2			Transceiver Speed Grade 3			Unit
Description		Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	
t _{pll_lock} (16)	_		_	10	_	_	10	_	_	10	μs

Notes to Table 23:

- (1) Speed grades shown in Table 23 refer to the PMA Speed Grade in the device ordering code. The maximum data rate could be restricted by the Core/PCS speed grade. Contact your Altera Sales Representative for the maximum data rate specifications in each speed grade combination offered. For more information about device ordering codes, refer to the *Stratix V Device Overview*.
- (2) The reference clock common mode voltage is equal to the V_{CCR_GXB} power supply level.
- (3) This supply must be connected to 1.0 V if the transceiver is configured at a data rate > 6.5 Gbps, and to 1.05 V if configured at a data rate > 10.3 Gbps when DFE is used. For data rates up to 6.5 Gbps, you can connect this supply to 0.85 V.
- (4) This supply follows VCCR_GXB.
- (5) The device cannot tolerate prolonged operation at this absolute maximum.
- (6) The differential eye opening specification at the receiver input pins assumes that **Receiver Equalization** is disabled. If you enable **Receiver Equalization**, the receiver circuitry can tolerate a lower minimum eye opening, depending on the equalization level.
- (7) The Quartus II software automatically selects the appropriate slew rate depending on the configured data rate or functional mode.
- (8) The input reference clock frequency options depend on the data rate and the device speed grade.
- (9) The line data rate may be limited by PCS-FPGA interface speed grade.
- (10) Refer to Figure 1 for the GX channel AC gain curves. The total effective AC gain is the AC gain minus the DC gain.
- (11) t_{LTR} is the time required for the receive CDR to lock to the input reference clock frequency after coming out of reset.
- (12) t_{I TD} is time required for the receiver CDR to start recovering valid data after the rx_is_lockedtodata signal goes high.
- (13) t_{LTD_manual} is the time required for the receiver CDR to start recovering valid data after the rx_is_lockedtodata signal goes high when the CDR is functioning in the manual mode.
- (14) t_{LTR_LTD_manual} is the time the receiver CDR must be kept in lock to reference (LTR) mode after the rx_is_lockedtoref signal goes high when the CDR is functioning in the manual mode.
- (15) $t_{pll\ powerdown}$ is the PLL powerdown minimum pulse width.
- (16) t_{nll lock} is the time required for the transmitter CMU/ATX PLL to lock to the input reference clock frequency after coming out of reset.
- (17) To calculate the REFCLK rms phase jitter requirement for PCle at reference clock frequencies other than 100 MHz, use the following formula: REFCLK rms phase jitter at f(MHz) = REFCLK rms phase jitter at 100 MHz × 100/f.
- (18) The maximum peak to peak differential input voltage V_{ID} after device configuration is equal to 4 × (absolute V_{MAX} for receiver pin V_{ICM}).
- (19) For ES devices, R_{REF} is 2000 Ω ±1%.
- (20) To calculate the REFCLK phase noise requirement at frequencies other than 622 MHz, use the following formula: REFCLK phase noise at f(MHz) = REFCLK phase noise at 622 MHz + 20*log(f/622).
- (21) SFP/+ optical modules require the host interface to have RD+/- differentially terminated with 100 Ω. The internal OCT feature is available after the Stratix V FPGA configuration is completed. Altera recommends that FPGA configuration is completed before inserting the optical module. Otherwise, minimize unnecessary removal and insertion with unconfigured devices.
- (22) Refer to Figure 2.
- (23) For oversampling designs to support data rates less than the minimum specification, the CDR needs to be in LTR mode only.
- (24) I3YY devices can achieve data rates up to 10.3125 Gbps.
- (25) When you use fPLL as a TXPLL of the transceiver.
- (26) REFCLK performance requires to meet transmitter REFCLK phase noise specification.
- (27) Minimum eye opening of 85 mV is only for the unstressed input eye condition.

Table 28. Transceiver Specifications for Stratix V GT Devices (Part 2 of 5) $^{(1)}$

Symbol/	Conditions	S	Transceive peed Grade			Transceive Deed Grade		Unit
Description		Min	Тур	Max	Min	Тур	Max	1
	100 Hz	_	_	-70	_	_	-70	
Transmitter REFCLK	1 kHz	_	_	-90		_	-90	
Phase Noise (622	10 kHz	_	_	-100	_	_	-100	dBc/Hz
MHz) ⁽¹⁸⁾	100 kHz	_	_	-110	_	_	-110	
	≥1 MHz		_	-120	_		-120	1
Transmitter REFCLK Phase Jitter (100 MHz) ⁽¹⁵⁾	10 kHz to 1.5 MHz (PCle)	_	_	3	_	_	3	ps (rms)
RREF (17)	_	_	1800 ± 1%	_	_	1800 ± 1%	_	Ω
Transceiver Clocks								
fixedclk clock frequency	PCIe Receiver Detect	_	100 or 125	_	_	100 or 125	_	MHz
Reconfiguration clock (mgmt_clk_clk) frequency		100	_	125	100		125	MHz
Receiver								
Supported I/O Standards	_		1.4-V PCML	, 1.5-V PCML	_, 2.5-V PCI	ML, LVPEC	L, and LVDS	6
Data rate (Standard PCS) (21)	GX channels	600	_	8500	600	_	8500	Mbps
Data rate (10G PCS) (21)	GX channels	600	_	12,500	600	_	12,500	Mbps
Data rate	GT channels	19,600	_	28,050	19,600	_	25,780	Mbps
Absolute V _{MAX} for a receiver pin ⁽³⁾	GT channels	_	_	1.2	_	_	1.2	V
Absolute V _{MIN} for a receiver pin	GT channels	-0.4	_	_	-0.4	_	_	V
Maximum peak-to-peak	GT channels		_	1.6	_		1.6	V
differential input voltage V _{ID} (diff p-p) before device configuration ⁽²⁰⁾	GX channels				(8)			
	GT channels							
Maximum peak-to-peak differential input voltage V _{ID} (diff p-p) after device configuration (16), (20)	$V_{CCR_GTB} = 1.05 \text{ V} $ $(V_{ICM} = 0.65 \text{ V})$	_	_	2.2	_	_	2.2	V
onfiguration (79), (29)	GX channels			<u> </u>	(8)		•	•
Minimum differential	GT channels	200	_	_	200		_	mV
eye opening at receiver serial input pins ⁽⁴⁾ , ⁽²⁰⁾	GX channels				(8)			

Table 29 shows the $\ensuremath{V_{\text{OD}}}$ settings for the GT channel.

Table 29. Typical V_{0D} Setting for GT Channel, TX Termination = 100 Ω

Symbol	V _{op} Setting	V _{op} Value (mV)
	0	0
	1	200
V differential peak to peak tunical (1)	2	400
V _{OD} differential peak to peak typical ⁽¹⁾	3	600
	4	800
	5	1000

Note:

(1) Refer to Figure 4.

Table 31. PLL Specifications for Stratix V Devices (Part 3 of 3)

	Symbol	Parameter	Min	Тур	Max	Unit
f	RES	Resolution of VCO frequency (f _{INPFD} = 100 MHz)	390625	5.96	0.023	Hz

Notes to Table 31:

- (1) This specification is limited in the Quartus II software by the I/O maximum frequency. The maximum I/O frequency is different for each I/O standard.
- (2) This specification is limited by the lower of the two: I/O f_{MAX} or f_{OUT} of the PLL.
- (3) A high input jitter directly affects the PLL output jitter. To have low PLL output clock jitter, you must provide a clean clock source < 120 ps.
- (4) f_{REF} is fIN/N when N = 1.
- (5) Peak-to-peak jitter with a probability level of 10⁻¹² (14 sigma, 99.9999999974404% confidence level). The output jitter specification applies to the intrinsic jitter of the PLL, when an input jitter of 30 ps is applied. The external memory interface clock output jitter specifications use a different measurement method and are available in Table 44 on page 52.
- (6) The cascaded PLL specification is only applicable with the following condition:
 - a. Upstream PLL: 0.59Mhz \le Upstream PLL BW < 1 MHz
 - b. Downstream PLL: Downstream PLL BW > 2 MHz
- (7) High bandwidth PLL settings are not supported in external feedback mode.
- (8) The external memory interface clock output jitter specifications use a different measurement method, which is available in Table 42 on page 50.
- (9) The VCO frequency reported by the Quartus II software in the PLL Usage Summary section of the compilation report takes into consideration the VCO post-scale counter K value. Therefore, if the counter K has a value of 2, the frequency reported can be lower than the f_{VCO} specification.
- (10) This specification only covers fractional PLL for low bandwidth. The f_{VCO} for fractional value range 0.05 0.95 must be \geq 1000 MHz, while f_{VCO} for fractional value range 0.20 0.80 must be \geq 1200 MHz.
- (11) This specification only covered fractional PLL for low bandwidth. The f_{VCO} for fractional value range 0.05-0.95 must be ≥ 1000 MHz.
- (12) This specification only covered fractional PLL for low bandwidth. The f_{VCO} for fractional value range 0.20-0.80 must be ≥ 1200 MHz.

DSP Block Specifications

Table 32 lists the Stratix V DSP block performance specifications.

Table 32. Block Performance Specifications for Stratix V DSP Devices (Part 1 of 2)

			F	Peformano	e			
Mode	C1	C2, C2L	12, 12L	C3	13, 13L, 13YY	C4	14	Unit
		Modes ι	ısing one	DSP				
Three 9 x 9	600	600	600	480	480	420	420	MHz
One 18 x 18	600	600	600	480	480	420	400	MHz
Two partial 18 x 18 (or 16 x 16)	600	600	600	480	480	420	400	MHz
One 27 x 27	500	500	500	400	400	350	350	MHz
One 36 x 18	500	500	500	400	400	350	350	MHz
One sum of two 18 x 18(One sum of 2 16 x 16)	500	500	500	400	400	350	350	MHz
One sum of square	500	500	500	400	400	350	350	MHz
One 18 x 18 plus 36 (a x b) + c	500	500	500	400	400	350	350	MHz
		Modes u	sing two I	OSPs				•
Three 18 x 18	500	500	500	400	400	350	350	MHz
One sum of four 18 x 18	475	475	475	380	380	300	300	MHz
One sum of two 27 x 27	465	465	450	380	380	300	290	MHz
One sum of two 36 x 18	475	475	475	380	380	300	300	MHz
One complex 18 x 18	500	500	500	400	400	350	350	MHz
One 36 x 36	475	475	475	380	380	300	300	MHz

Table 33. Memory Block Performance Specifications for Stratix V Devices (1), (2) (Part 2 of 2)

		Resour	ces Used			Pe	erforman	ce			
Memory	Mode	ALUTS	Memory	C1	C2, C2L	C3	C4	12, 12L	13, 13L, 13YY	14	Unit
	Single-port, all supported widths	0	1	700	700	650	550	700	500	450	MHz
	Simple dual-port, all supported widths	0	1	700	700	650	550	700	500	450	MHz
	Simple dual-port with the read-during-write option set to Old Data , all supported widths	0	1	525	525	455	400	525	455	400	MHz
M20K Block	Simple dual-port with ECC enabled, 512 × 32	0	1	450	450	400	350	450	400	350	MHz
	Simple dual-port with ECC and optional pipeline registers enabled, 512 × 32	0	1	600	600	500	450	600	500	450	MHz
	True dual port, all supported widths	0	1	700	700	650	550	700	500	450	MHz
	ROM, all supported widths	0	1	700	700	650	550	700	500	450	MHz

Notes to Table 33:

Temperature Sensing Diode Specifications

Table 34 lists the internal TSD specification.

Table 34. Internal Temperature Sensing Diode Specification

Tei	mperature Range	Accuracy	Offset Calibrated Option	Sampling Rate	Conversion Time	Resolution	Minimum Resolution with no Missing Codes
-40°	°C to 100°C	±8°C	No	1 MHz, 500 KHz	< 100 ms	8 bits	8 bits

Table 35 lists the specifications for the Stratix V external temperature sensing diode.

Table 35. External Temperature Sensing Diode Specifications for Stratix V Devices

Description	Min	Тур	Max	Unit
I _{bias} , diode source current	8	_	200	μΑ
V _{bias,} voltage across diode	0.3	_	0.9	V
Series resistance	_	_	<1	Ω
Diode ideality factor	1.006	1.008	1.010	_

⁽¹⁾ To achieve the maximum memory block performance, use a memory block clock that comes through global clock routing from an on-chip PLL set to **50%** output duty cycle. Use the Quartus II software to report timing for this and other memory block clocking schemes.

⁽²⁾ When you use the error detection cyclical redundancy check (CRC) feature, there is no degradation in F_{MAX}.

⁽³⁾ The F_{MAX} specification is only achievable with Fitter options, **MLAB Implementation In 16-Bit Deep Mode** enabled.

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Table 36. High-Speed I/O Specifications for Stratix V Devices (1), (2) (Part 3 of 4)

			C1		C2,	C2L, I	2, I2L	C3,	13, I3L	., I3YY		C4,I4	4	
Symbol	Conditions	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
t _{DUTY}	Transmitter output clock duty cycle for both True and Emulated Differential I/O Standards	45	50	55	45	50	55	45	50	55	45	50	55	%
	True Differential I/O Standards	_	_	160	_	_	160	_	_	200	_	_	200	ps
t _{RISE} & t _{FALL}	Emulated Differential I/O Standards with three external output resistor networks	_		250	_	_	250	_		250	_		300	ps
	True Differential I/O Standards	_	_	150	_		150		_	150		_	150	ps
TCCS	Emulated Differential I/O Standards	_	_	300	_	_	300	_		300	_		300	ps
Receiver														
	SERDES factor J = 3 to 10 (11), (12), (13), (14), (15), (16)	150	_	1434	150	_	1434	150	_	1250	150	_	1050	Mbps
True Differential I/O Standards	SERDES factor J ≥ 4 LVDS RX with DPA (12), (14), (15), (16)	150	_	1600	150	_	1600	150	_	1600	150	_	1250	Mbps
- f _{HSDRDPA} (data rate)	SERDES factor J = 2, uses DDR Registers	(6)	_	(7)	(6)	_	(7)	(6)		(7)	(6)		(7)	Mbps
	SERDES factor J = 1, uses SDR Register	(6)	_	(7)	(6)	_	(7)	(6)		(7)	(6)	_	(7)	Mbps

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Table 48. Minimum Configuration Time Estimation for Stratix V Devices

	Mombou		Active Serial (1)	1	Fast Passive Parallel (2)				
Variant	Member Code	Width DCLK (MHz)		Min Config Time (s)	Width	DCLK (MHz)	Min Config Time (s)		
	D3	4	100	0.344	32	100	0.043		
	D/I	4	100	0.534	32	100	0.067		
GS	D4	4	100	0.344	32	100	0.043		
us	D5	4	100	0.534	32	100	0.067		
	D6	4	100	0.741	32	100	0.093		
	D8	4	100	0.741	32	100	0.093		
E	E9	4	100	0.857	32	100	0.107		
_	EB	4	100	0.857	32	100	0.107		

Notes to Table 48:

Fast Passive Parallel Configuration Timing

This section describes the fast passive parallel (FPP) configuration timing parameters for Stratix V devices.

DCLK-to-DATA[] Ratio for FPP Configuration

FPP configuration requires a different DCLK-to-DATA[] ratio when you enable the design security, decompression, or both features. Table 49 lists the DCLK-to-DATA[] ratio for each combination.

Table 49. DCLK-to-DATA[] Ratio (1) (Part 1 of 2)

Configuration Scheme	Decompression	Design Security	DCLK-to-DATA[] Ratio
	Disabled	Disabled	1
FPP ×8	Disabled	Enabled	1
IFF X0	Enabled	Disabled	2
	Enabled	Enabled	2
	Disabled	Disabled	1
FPP ×16	Disabled	Enabled	2
IFF XIO	Enabled	Disabled	4
	Enabled	Enabled	4

⁽¹⁾ DCLK frequency of 100 MHz using external CLKUSR.

⁽²⁾ Max FPGA FPP bandwidth may exceed bandwidth available from some external storage or control logic.

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Table 49. DCLK-to-DATA[] Ratio (1) (Part 2 of 2)

Configuration Scheme	Decompression	Design Security	DCLK-to-DATA[] Ratio
	Disabled	Disabled	1
FPP ×32	Disabled	Enabled	4
	Enabled	Disabled	8
	Enabled	Enabled	8

Note to Table 49:

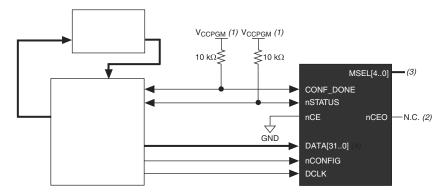
(1) Depending on the DCLK-to-DATA [] ratio, the host must send a DCLK frequency that is r times the data rate in bytes per second (Bps), or words per second (Wps). For example, in FPP ×16 when the DCLK-to-DATA [] ratio is 2, the DCLK frequency must be 2 times the data rate in Wps. Stratix V devices use the additional clock cycles to decrypt and decompress the configuration data.



If the DCLK-to-DATA[] ratio is greater than 1, at the end of configuration, you can only stop the DCLK (DCLK-to-DATA[] ratio -1) clock cycles after the last data is latched into the Stratix V device.

Figure 11 shows the configuration interface connections between the Stratix V device and a MAX II or MAX V device for single device configuration.

Figure 11. Single Device FPP Configuration Using an External Host



Notes to Figure 11:

- (1) Connect the resistor to a supply that provides an acceptable input signal for the Stratix V device. V_{CCPGM} must be high enough to meet the V_{IH} specification of the I/O on the device and the external host. Altera recommends powering up all configuration system I/Os with V_{CCPGM}.
- (2) You can leave the nceo pin unconnected or use it as a user I/O pin when it does not feed another device's nce pin.
- (3) The MSEL pin settings vary for different data width, configuration voltage standards, and POR delay. To connect MSEL, refer to the MSEL Pin Settings section of the "Configuration, Design Security, and Remote System Upgrades in Stratix V Devices" chapter.
- (4) If you use FPP $\times 8$, use DATA [7..0]. If you use FPP $\times 16$, use DATA [15..0].

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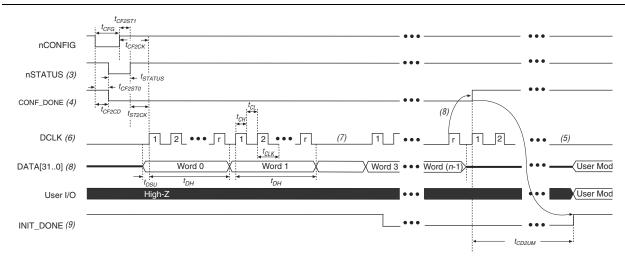


Figure 13. FPP Configuration Timing Waveform When the DCLK-to-DATA[] Ratio is >1 (1), (2)

Notes to Figure 13:

- (1) Use this timing waveform and parameters when the DCLK-to-DATA [] ratio is >1. To find out the DCLK-to-DATA [] ratio for your system, refer to Table 49 on page 55.
- (2) The beginning of this waveform shows the device in user mode. In user mode, nconfig, nstatus, and conf_done are at logic high levels. When nconfig is pulled low, a reconfiguration cycle begins.
- (3) After power-up, the Stratix V device holds nSTATUS low for the time as specified by the POR delay.
- (4) After power-up, before and during configuration, CONF DONE is low.
- (5) Do not leave DCLK floating after configuration. You can drive it high or low, whichever is more convenient.
- (6) "r" denotes the DCLK-to-DATA[] ratio. For the DCLK-to-DATA[] ratio based on the decompression and the design security feature enable settings, refer to Table 49 on page 55.
- (7) If needed, pause DCLK by holding it low. When DCLK restarts, the external host must provide data on the DATA [31..0] pins prior to sending the first DCLK rising edge.
- (8) To ensure a successful configuration, send the entire configuration data to the Stratix V device. CONF_DONE is released high after the Stratix V device receives all the configuration data successfully. After CONF_DONE goes high, send two additional falling edges on DCLK to begin initialization and enter user mode.
- (9) After the option bit to enable the INIT DONE pin is configured into the device, the INIT DONE goes low.

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Active Serial Configuration Timing

Table 52 lists the DCLK frequency specification in the AS configuration scheme.

Table 52. DCLK Frequency Specification in the AS Configuration Scheme (1), (2)

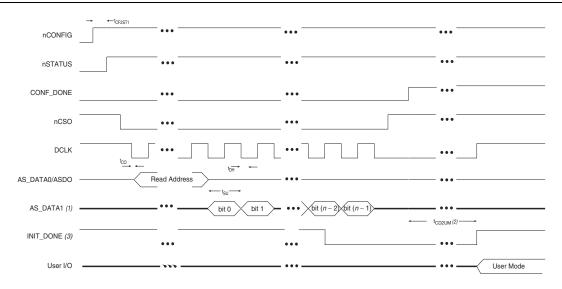
Minimum	Typical	Maximum	Unit
5.3	7.9	12.5	MHz
10.6	15.7	25.0	MHz
21.3	31.4	50.0	MHz
42.6	62.9	100.0	MHz

Notes to Table 52:

- This applies to the DCLK frequency specification when using the internal oscillator as the configuration clock source.
- (2) The AS multi-device configuration scheme does not support DCLK frequency of 100 MHz.

Figure 14 shows the single-device configuration setup for an AS ×1 mode.

Figure 14. AS Configuration Timing



Notes to Figure 14:

- (1) If you are using AS ×4 mode, this signal represents the AS_DATA [3..0] and EPCQ sends in 4-bits of data for each DCLK cycle.
- (2) The initialization clock can be from internal oscillator or ${\tt CLKUSR}$ pin.
- (3) After the option bit to enable the $INIT_DONE$ pin is configured into the device, the $INIT_DONE$ goes low.

Table 53 lists the timing parameters for AS $\times 1$ and AS $\times 4$ configurations in Stratix V devices.

Table 53. AS Timing Parameters for AS \times 1 and AS \times 4 Configurations in Stratix V Devices (1), (2) (Part 1 of 2)

Symbol	Parameter	Minimum	Maximum	Units
t _{CO}	DCLK falling edge to AS_DATAO/ASDO output	_	2	ns
t _{SU}	Data setup time before falling edge on DCLK	1.5	_	ns
t _H	Data hold time after falling edge on DCLK	0	_	ns

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Table 53. AS Timing Parameters for AS \times 1 and AS \times 4 Configurations in Stratix V Devices (1), (2) (Part 2 of 2)

Symbol	Parameter	Minimum	Maximum	Units
t _{CD2UM}	CONF_DONE high to user mode (3)	175	437	μS
t _{CD2CU}	CONF_DONE high to CLKUSR enabled	4 × maximum DCLK period	_	_
t _{CD2UMC}	CONF_DONE high to user mode with CLKUSR option on	$\begin{array}{c} t_{\text{CD2CU}} + (8576 \times \\ \text{CLKUSR period}) \end{array}$	_	_

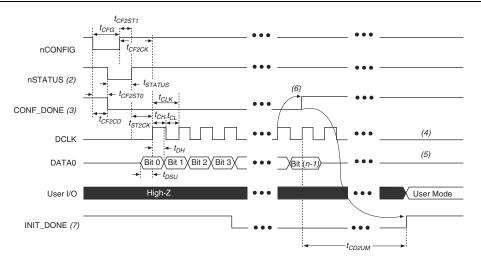
Notes to Table 53:

- (1) The minimum and maximum numbers apply only if you choose the internal oscillator as the clock source for initializing the device.
- $(2) \quad t_{\text{CF2CD}}, t_{\text{CF2ST0}}, t_{\text{CFG}}, t_{\text{STATUS}}, \text{ and } t_{\text{CF2ST1}} \text{ timing parameters are identical to the timing parameters for PS mode listed in Table 54 on page 63}.$
- (3) To enable the CLKUSR pin as the initialization clock source and to obtain the maximum frequency specification on this pin, refer to the Initialization section of the "Configuration, Design Security, and Remote System Upgrades in Stratix V Devices" chapter.

Passive Serial Configuration Timing

Figure 15 shows the timing waveform for a passive serial (PS) configuration when using a MAX II device, MAX V device, or microprocessor as an external host.

Figure 15. PS Configuration Timing Waveform (1)



Notes to Figure 15:

- (1) The beginning of this waveform shows the device in user mode. In user mode, nCONFIG, nSTATUS, and CONF_DONE are at logic high levels. When nCONFIG is pulled low, a reconfiguration cycle begins.
- (2) After power-up, the Stratix V device holds nSTATUS low for the time of the POR delay.
- (3) After power-up, before and during configuration, CONF DONE is low.
- (4) Do not leave DCLK floating after configuration. You can drive it high or low, whichever is more convenient.
- (5) DATAO is available as a user I/O pin after configuration. The state of this pin depends on the dual-purpose pin settings in the **Device and Pins Option**.
- (6) To ensure a successful configuration, send the entire configuration data to the Stratix V device. CONF_DONE is released high after the Stratix V device receives all the configuration data successfully. After CONF_DONE goes high, send two additional falling edges on DCLK to begin initialization and enter user mode.
- (7) After the option bit to enable the INIT DONE pin is configured into the device, the INIT DONE goes low.

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Document Revision History

Table 61 lists the revision history for this chapter.

Table 61. Document Revision History (Part 1 of 3)

Date	Version	Changes
June 2018	3.9	■ Added the "Stratix V Device Overshoot Duration" figure.
April 2017		■ Added a footnote to the "High-Speed I/O Specifications for Stratix V Devices" table.
	3.8	■ Changed the minimum value for t _{CD2UMC} in the "PS Timing Parameters for Stratix V Devices" table.
		■ Changed the condition for 100-Ω R _D in the "OCT Without Calibration Resistance Tolerance Specifications for Stratix V Devices" table.
		■ Changed the minimum value for t _{CD2UMC} in the "AS Timing Parameters for AS '1 and AS '4 Configurations in Stratix V Devices" table
		■ Changed the minimum value for t _{CD2UMC} in the "FPP Timing Parameters for Stratix V Devices When the DCLK-to-DATA[] Ratio is >1" table.
		■ Changed the minimum value for t _{CD2UMC} in the "FPP Timing Parameters for Stratix V Devices When the DCLK-to-DATA[] Ratio is >1" table.
		■ Changed the minimum number of clock cycles value in the "Initialization Clock Source Option and the Maximum Frequency" table.
June 2016	3.7	■ Added the V _{ID} minimum specification for LVPECL in the "Differential I/O Standard Specifications for Stratix V Devices" table
		■ Added the I _{OUT} specification to the "Absolute Maximum Ratings for Stratix V Devices" table.
December 2015	3.6	■ Added a footnote to the "High-Speed I/O Specifications for Stratix V Devices" table.
December 2015	3.5	■ Changed the transmitter, receiver, and ATX PLL data rate specifications in the "Transceiver Specifications for Stratix V GX and GS Devices" table.
		■ Changed the configuration .rbf sizes in the "Uncompressed .rbf Sizes for Stratix V Devices" table.
	3.4	■ Changed the data rate specification for transceiver speed grade 3 in the following tables:
		"Transceiver Specifications for Stratix V GX and GS Devices"
		■ "Stratix V Standard PCS Approximate Maximum Date Rate"
		■ "Stratix V 10G PCS Approximate Maximum Data Rate"
July 2015		■ Changed the conditions for reference clock rise and fall time, and added a note to the "Transceiver Specifications for Stratix V GX and GS Devices" table.
		■ Added a note to the "Minimum differential eye opening at receiver serial input pins" specification in the "Transceiver Specifications for Stratix V GX and GS Devices" table.
		■ Changed the t _{CO} maximum value in the "AS Timing Parameters for AS '1 and AS '4 Configurations in Stratix V Devices" table.
		■ Removed the CDR ppm tolerance specification from the "Transceiver Specifications for Stratix V GX and GS Devices" table.

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Table 61. Document Revision History (Part 3 of 3)

■ Updated Table 2, Table 6, Table 7, Table 20, Table 23, Table 27, Table 47, Table 2013 2.7 ■ Added Table 24, Table 48 ■ Updated Figure 9, Figure 10, Figure 11, Figure 12 ■ Updated Table 7, Table 9, Table 20, Table 23, Table 27, Table 30, Table 31, Table 46 ■ Updated "Maximum Allowed Overshoot and Undershoot Voltage" ■ Updated "Maximum Allowed Overshoot and Undershoot Voltage" ■ Updated Table 3, Table 6, Table 7, Table 8, Table 23, Table 24, Table 25, TaTable 30, Table 32, Table 35 ■ Added Table 33 ■ Added "Fast Passive Parallel Configuration Timing" ■ Added "Added "Passive Serial Configuration Timing" ■ Added "Passive Serial Configuration Timing" ■ Added "Remote System Upgrades" ■ Added "Initialization" ■ Added "Initialization" ■ Added "Raw Binary File Size" ■ Added Figure 1, Figure 2, and Figure 3. ■ Updated Table 1, Table 2, Table 3, Table 6, Table 11, Table 22, Table 23, Table 40, Table 4 Table 56, and Table 59. ■ Various edits throughout to fix bugs.	
December 2012 2.5 December 2012 D	able 60
December 2012 2.6 Updated Table 7, Table 9, Table 20, Table 23, Table 27, Table 30, Table 31, Table 46 Updated "Maximum Allowed Overshoot and Undershoot Voltage" Updated Table 3, Table 6, Table 7, Table 8, Table 23, Table 24, Table 25, Tatable 30, Table 32, Table 35 Added Table 33 Added "Fast Passive Parallel Configuration Timing" Added "Active Serial Configuration Timing" Added "Passive Serial Configuration Timing" Added "Remote System Upgrades" Added "User Watchdog Internal Circuitry Timing Specification" Added "Raw Binary File Size" Added "Raw Binary File Size" Added Table 1, Table 2, Table 3, Table 6, Table 11, Table 22, Table 23, Table 30, Table 31, Table 32, Table 35, Table 38, Table 39, Table 40, Table 4 Table 56, and Table 59.	
Table 46 Updated "Maximum Allowed Overshoot and Undershoot Voltage" Updated Table 3, Table 6, Table 7, Table 8, Table 23, Table 24, Table 25, Ta Table 30, Table 32, Table 35 Added Table 33 Added "Fast Passive Parallel Configuration Timing" Added "Active Serial Configuration Timing" Added "Passive Serial Configuration Timing" Added "Remote System Upgrades" Added "User Watchdog Internal Circuitry Timing Specification" Added "Initialization" Added "Raw Binary File Size" Added Table 1, Table 2, Table 3, Table 6, Table 11, Table 22, Table 23, Table 40, Table 40, Table 40, Table 56, and Table 59.	
Updated "Maximum Allowed Overshoot and Undershoot Voltage" Updated Table 3, Table 6, Table 7, Table 8, Table 23, Table 24, Table 25, Ta Table 30, Table 32, Table 35 Added Table 33 Added "Fast Passive Parallel Configuration Timing" Added "Active Serial Configuration Timing" Added "Passive Serial Configuration Timing" Added "Remote System Upgrades" Added "User Watchdog Internal Circuitry Timing Specification" Added "Initialization" Added "Raw Binary File Size" Added Figure 1, Figure 2, and Figure 3. Updated Table 1, Table 2, Table 3, Table 6, Table 11, Table 22, Table 23, Table 40, Table 40, Table 40, Table 56, and Table 59.	Table 35,
December 2012 2.5 Updated Table 3, Table 6, Table 7, Table 8, Table 23, Table 24, Table 25, Table 30, Table 32, Table 35 Added Table 33 Added "Fast Passive Parallel Configuration Timing" Added "Active Serial Configuration Timing" Added "Passive Serial Configuration Timing" Added "Remote System Upgrades" Added "User Watchdog Internal Circuitry Timing Specification" Added "Initialization" Added "Raw Binary File Size" Added Figure 1, Figure 2, and Figure 3. Updated Table 1, Table 2, Table 3, Table 6, Table 11, Table 22, Table 23, Table 7, Table 30, Table 31, Table 32, Table 38, Table 39, Table 40, Table 4, Table 56, and Table 59.	
Table 30, Table 35 Added Table 33 Added "Fast Passive Parallel Configuration Timing" Added "Active Serial Configuration Timing" Added "Passive Serial Configuration Timing" Added "Remote System Upgrades" Added "User Watchdog Internal Circuitry Timing Specification" Added "Initialization" Added "Raw Binary File Size" Added Figure 1, Figure 2, and Figure 3. Updated Table 1, Table 2, Table 3, Table 6, Table 11, Table 22, Table 23, Table 7 Table 30, Table 31, Table 32, Table 35, Table 38, Table 39, Table 40, Table 4 Table 56, and Table 59.	
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December 2012 Added "Active Serial Configuration Timing" Added "Passive Serial Configuration Timing" Added "Remote System Upgrades" Added "User Watchdog Internal Circuitry Timing Specification" Added "Initialization" Added "Raw Binary File Size" Added Figure 1, Figure 2, and Figure 3. Updated Table 1, Table 2, Table 3, Table 6, Table 11, Table 22, Table 23, Table Table 30, Table 31, Table 32, Table 35, Table 38, Table 39, Table 40, Table 4 Table 56, and Table 59.	
December 2012 2.5 Added "Passive Serial Configuration Timing" Added "Remote System Upgrades" Added "User Watchdog Internal Circuitry Timing Specification" Added "Initialization" Added "Raw Binary File Size" Added Figure 1, Figure 2, and Figure 3. Updated Table 1, Table 2, Table 3, Table 6, Table 11, Table 22, Table 23, Table Table 30, Table 31, Table 32, Table 35, Table 38, Table 39, Table 40, Table 4 Table 56, and Table 59.	
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■ Added "Initialization" ■ Added "Raw Binary File Size" ■ Added Figure 1, Figure 2, and Figure 3. ■ Updated Table 1, Table 2, Table 3, Table 6, Table 11, Table 22, Table 23, Table Table 30, Table 31, Table 32, Table 35, Table 38, Table 39, Table 40, Table 4 Table 56, and Table 59.	
■ Added "Raw Binary File Size" ■ Added Figure 1, Figure 2, and Figure 3. ■ Updated Table 1, Table 2, Table 3, Table 6, Table 11, Table 22, Table 23, Table Table 30, Table 31, Table 32, Table 35, Table 38, Table 39, Table 40, Table 4 Table 56, and Table 59.	
June 2012 Added Figure 1, Figure 2, and Figure 3. Updated Table 1, Table 2, Table 3, Table 6, Table 11, Table 22, Table 23, Table 36, Table 36, Table 37, Table 38, Table 39, Table 40, Table 40, Table 56, and Table 59.	
June 2012 Updated Table 1, Table 2, Table 3, Table 6, Table 11, Table 22, Table 23, Table 30, Table 31, Table 32, Table 35, Table 38, Table 39, Table 40, Table 4 Table 56, and Table 59.	
Table 30, Table 31, Table 35, Table 38, Table 39, Table 40, Table 4 Table 56, and Table 59.	
■ Changed title of document to <i>Stratix V Device Datasheet</i> .	
■ Removed document from the Stratix V handbook and made it a separate document	cument.
February 2012 2.3 Updated Table 1–22, Table 1–29, Table 1–31, and Table 1–31.	
December 2011 2.2 ■ Added Table 2–31.	
■ Updated Table 2–28 and Table 2–34.	
■ Added Table 2–2 and Table 2–21 and updated Table 2–5 with information at Stratix V GT devices.	out
November 2011 2.1 Updated Table 2–11, Table 2–13, Table 2–20, and Table 2–25.	
■ Various edits throughout to fix SPRs.	
■ Updated Table 2–4, Table 2–18, Table 2–19, Table 2–21, Table 2–22, Table 2 Table 2–24.	2–23, and
May 2011 2.0 ■ Updated the "DQ Logic Block and Memory Output Clock Jitter Specifications	s" title.
■ Chapter moved to Volume 1.	
■ Minor text edits.	
■ Updated Table 1–2, Table 1–4, Table 1–19, and Table 1–23.	
December 2010 1.1 Converted chapter to the new template.	
■ Minor text edits.	
July 2010 1.0 Initial release.	